

N-Channel Enhancement Mode Power MOSFET

Description

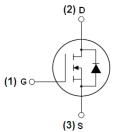
The RM100N30DF uses advanced trench technology and design to provide excellent $R_{DS(ON)}$ with low gate charge. It can be used in a wide variety of applications.

General Features

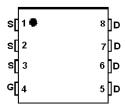
- V_{DS} =30V,I_D =100A
 - $R_{DS(ON)}$ <2.5 m Ω @ V_{GS}=10V
 - $R_{DS(ON)}$ <3.5m Ω @ V_{GS}=4.5V
- High density cell design for ultra low Rdson
- Fully characterized avalanche voltage and current
- Good stability and uniformity with high E_{AS}
- Excellent package for good heat dissipation
- Special process technology for high ESD capability

Application

- Power switching application
- Hard switched and high frequency circuits
- Uninterruptible power supply
- Halogen-free



Schematic diagram



Marking and pin assignment



DFN5X6-8L top view

Package Marking and Ordering Information

Device Marking	Device	Device Package	Reel Size	Tape width	Quantity
100N30	RM100N30DF	DFN5X6-8L	-	-	-

Absolute Maximum Ratings (T_c=25 $^{\circ}$ Cunless otherwise noted)

Parameter	Symbol	Limit	Unit
Drain-Source Voltage	Vds	30	V
Gate-Source Voltage	Vgs	±20	V
Drain Current-Continuous	Ι _D	100	А
Drain Current-Continuous(T _C =100℃)	I _D (100℃)	70.7	A
Pulsed Drain Current	I _{DM}	300	A
Maximum Power Dissipation	PD	65	W
Derating factor		0.43	W/°C
Operating Junction and Storage Temperature Range	TJ,TSTG	-55 To 175	°C

Thermal Characteristic

Thermal Resistance, Junction-to-Case ^(Note 2)	$R_{ extsf{ heta}JC}$	2.3	°C /W

Electrical Characteristics (T_c=25 $^\circ\!\mathrm{C}$ unless otherwise noted)

Parameter	Symbol	Condition	Min	Тур	Max	Unit
Off Characteristics	·		•	•		
Drain-Source Breakdown Voltage	BV _{DSS}	V _{GS} =0V I _D =250µA	30	35	-	V
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} =30V,V _{GS} =0V	-	-	1	μA
Gate-Body Leakage Current	I _{GSS}	V _{GS} =±20V,V _{DS} =0V	-	-	±100	nA
On Characteristics (Note 3)	ł	•	•	•		
Gate Threshold Voltage	V _{GS(th)}	V _{DS} =V _{GS} ,I _D =250µA	1.2	1.7	2.5	V
Durin Original Original Designment	Р	V _{GS} =10V, I _D =20A	-	1.9	2.5	
Drain-Source On-State Resistance	R _{DS(ON)}	V _{GS} =4.5V, I _D =10A		2.9	3.5	mΩ
Forward Transconductance	g fs	V _{DS} =10V,I _D =20A	32	-	-	S
Dynamic Characteristics (Note4)	·		•	•		
Input Capacitance	C _{lss}	- V _{DS} =15V,V _{GS} =0V, F=1.0MHz	-	5000	-	PF
Output Capacitance	C _{oss}		-	1135	-	PF
Reverse Transfer Capacitance	C _{rss}		-	563	-	PF
Switching Characteristics (Note 4)	ł	•	•	•		
Turn-on Delay Time	t _{d(on)}		-	26	-	nS
Turn-on Rise Time	tr	V_{DD} =15V, R _L =15 Ω	-	24	-	nS
Turn-Off Delay Time	t _{d(off)}	V _{GS} =10V,R _G =2.5Ω	-	91	-	nS
Turn-Off Fall Time	t _f		-	39	-	nS
Total Gate Charge	Qg		-	38		nC
Gate-Source Charge	Q _{gs}	V _{DS} =15V,I _D =20A, V _{GS} =10V	-	9		nC
Gate-Drain Charge	Q _{gd}	V _{GS} =10V	-	13		nC
Drain-Source Diode Characteristics	I		•			•
Diode Forward Voltage (Note 3)	V _{SD}	V _{GS} =0V,I _S =10A	-		1.2	V
Diode Forward Current (Note 2)	Is		-	-	100	A
Reverse Recovery Time	t _{rr}	TJ = 25°C, IF = 20A	-	42	-	nS
Reverse Recovery Charge	Qrr	di/dt = 100A/µs ^(Note3)	-	39	-	nC
Forward Turn-On Time	t _{on}	Intrinsic turn-on time is negl	igible (turi	n-on is do	ominated b	y LS+LD)

Notes:

1. Repetitive Rating: Pulse width limited by maximum junction temperature.

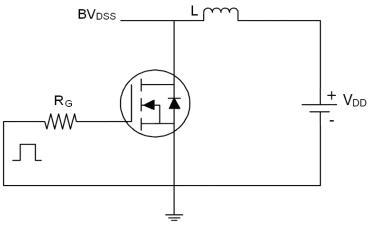
2. Surface Mounted on FR4 Board, $t \le 10$ sec.

3. Pulse Test: Pulse Width \leq 300µs, Duty Cycle \leq 2%.

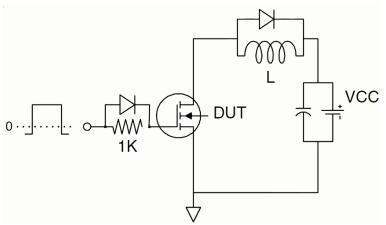
4. Guaranteed by design, not subject to production



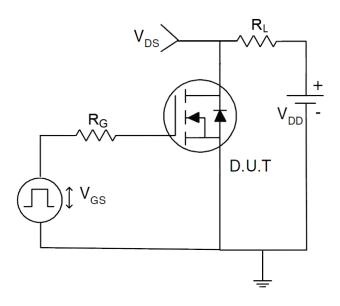
Test circuit 1) E_{AS} Test Circuit



2) Gate Charge Test Circuit

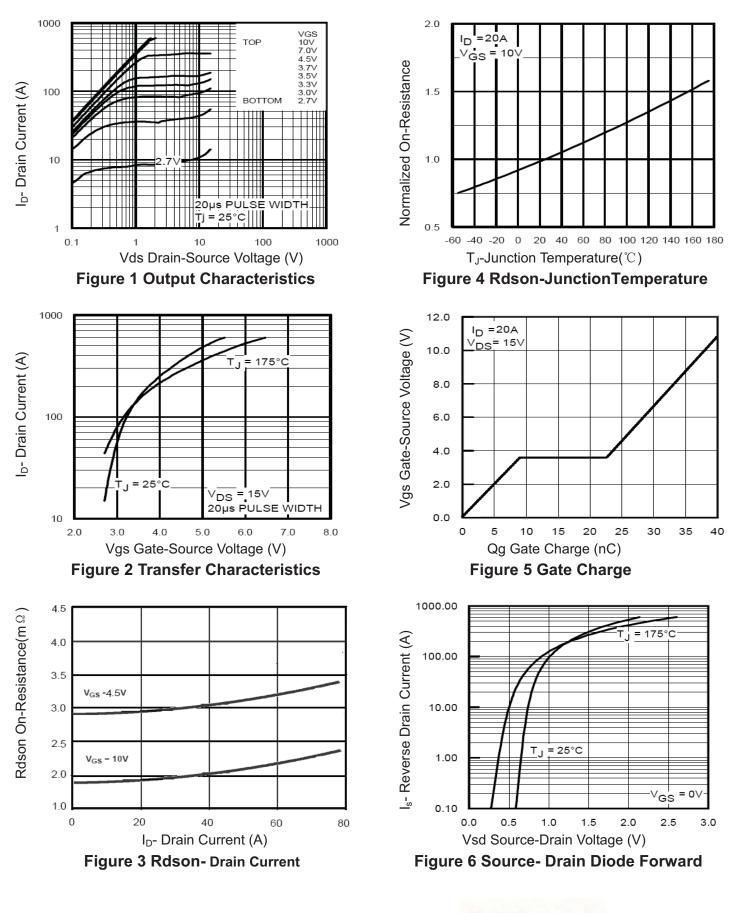


3) Switch Time Test Circuit





RATING AND CHARACTERISTICS CURVES (RM100N30DF)



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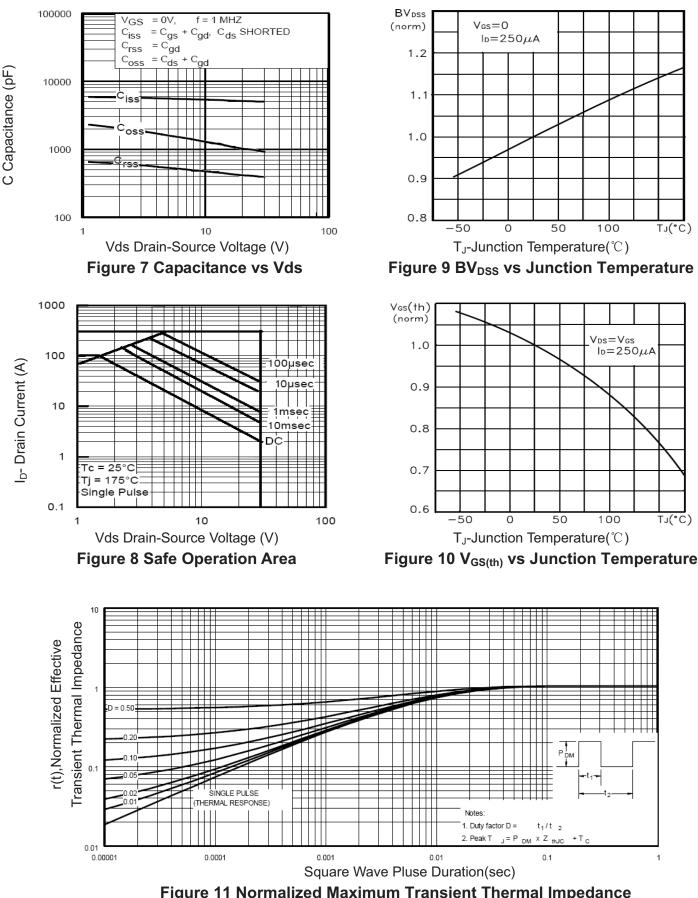
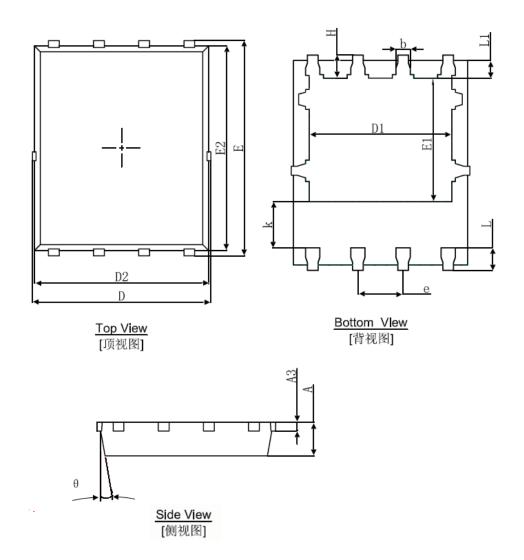


Figure 11 Normalized Maximum Transient Thermal Impedance

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DFN5X6-8L Package Information



Cumula of	Dimensions In Millimeters		Dimensions In Inches		
Symbol -	Min.	Max.	Min.	Max.	
A	0.900	1.000	0.035	0.039	
A3	0.254	REF.	0.010	REF.	
D	4.944	5.096	0.195	0.201	
E	5.974	6.126	0.235	0.241	
D1	3.910	4.110	0.154	0.162	
E1	3.375	3.575	0.133	0.141	
D2	4.824	4.976	0.190	0.196	
E2	5.674	5.826	0.223	0.229	
k	1.190	1.390	0.047	0.055	
b	0.350	0.450	0.014	0.018	
е	1.270TYP.		0.050TYP.		
L	0.559	0.711	0.022	0.028	
L1	0.424	0.576	0.017	0.023	
Н	0.574	0.726	0.023	0.029	
θ	8°	12°	8°	12°	

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